

### BAL-NRF01D3

# 50 ohm balun transformer for 2G45 ISM matched Nordic's chipset: nRF24LE1 QFN32, nRF24AP2-1CH and nRF24AP2-8CH

Datasheet - production data

#### **Features**

- 50 Ω nominal input / conjugate match to nRF24LE1 QFN32, nRF24AP2-1CH and nRF24AP2-8CH
- Low insertion loss
- Low amplitude imbalance
- Low phase imbalance
- Small footprint: < 1.5 mm<sup>2</sup>

#### **Benefits**

- Very low profile: < 595 µm after reflow
- High RF performance
- RF BOM and area reduction

#### **Applications**

- 2.45 GHz impedance matched balun filter
- Optimized for Nordic's Chipset nRF24LE1/AP2

## **Description**

STMicroelectronics BAL-NRF01D3 is an ultraminiature balun. The BAL-NRF01D3 integrates matching network and harmonics filter. Matching impedance has been customized for the following Nordic Semiconductor circuits: nRF24LE1 QFN-32 pins, nRF24AP2-1CH and nRF24AP2-8CH. The BAL-NRF01D3 uses STMicroelectronics IPD technology on non conductive glass substrate which optimize RF performances. The BAL-NRF01D3 has been tested and approved by Nordic Semiconductor in their nRF2723 nRFgo module.

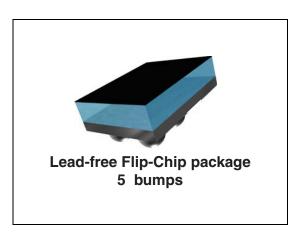
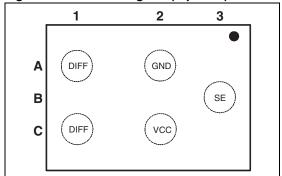


Figure 1. Pinout diagram (top view)



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This is information on a product in full production.

Characteristics BAL-NRF01D3

## 1 Characteristics

Table 1. Absolute maximum ratings (limiting values)

Cumbal	Parameter		Value			
Symbol			Тур.	Max.	Unit	
P <sub>IN</sub>	Input Power RFIN			20	dBm	
	ESD ratings MIL STD883C (HBM: C = 100 pF, R = 1.5 k $\Omega$ , air discharge)	2000			_ v	
V <sub>ESD</sub>	ESD ratings charge device model (JESD22-C101-C)	500				
	ESD ratings machine model (MM: C = 200 pF, R = 25 $\Omega$ , L = 500 nH)	200				
T <sub>OP</sub>	Operating temperature	-40		+85	°C	

Table 2. Impedances  $(T_{amb} = 25 \,^{\circ}C)$ 

Symbol	Parameter	Value			Unit
Symbol	Farameter	Min.	Тур.	Max.	Oille
Z <sub>OUT</sub>	Nominal differential output impedance		conjugate match to nRF24LE1/AP2		Ω
Z <sub>IN</sub>	Nominal input impedance		50		Ω

Table 3. RF performance ( $T_{amb} = 25 \,^{\circ}C$ )

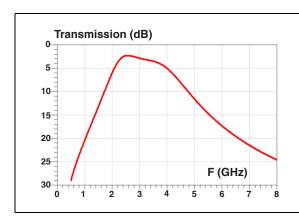
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Symbol	Parameter	Test condition	Value			Unit
		rest condition	Min.	Тур.	Max.	Oilit
F	Frequency range (bandwidth)		2400		2540	MHz
ΙL	Insertion loss in bandwidth			2.25		dB
$R_L$	Return loss in bandwidth			10		dB
фimb	Phase imbalance			3		0
Aimb	Amplitude imbalance			0.1		dB
2f0	2nd harmonic filtering	4880 MHz		10		dB
3f0	3rd harmonic filtering	7320 MHz		20		dB

BAL-NRF01D3 Characteristics

#### 1.1 On-board simulations

Figure 2. Insertion loss ( $T_{amb} = 25 \, ^{\circ}C$ )

Figure 3. Return loss @ single port  $(T_{amb} = 25 \,^{\circ}C)$ 



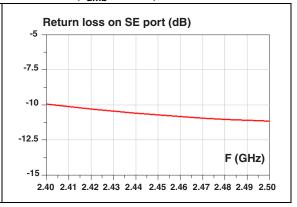
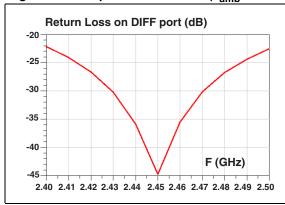


Figure 4. Amplitude imbalance ( $T_{amb}$  = 25 °C) Figure 5. Phase imbalance ( $T_{amb}$  = 25 °C)



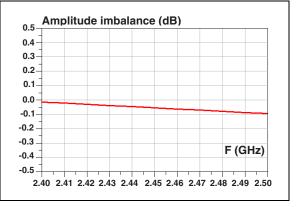
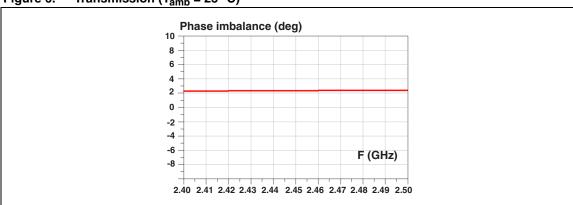


Figure 6. Transmission ( $T_{amb} = 25 \,^{\circ}C$ )



## 2 Application information

Figure 7. Application schematic (courtesy of Nordic Semiconductor

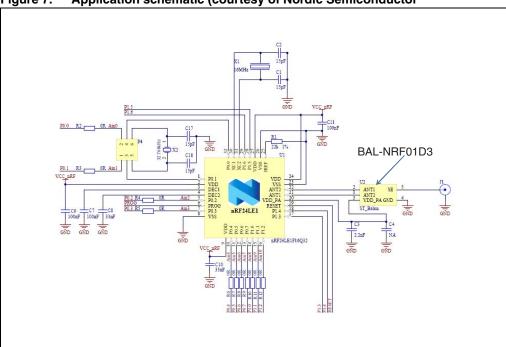
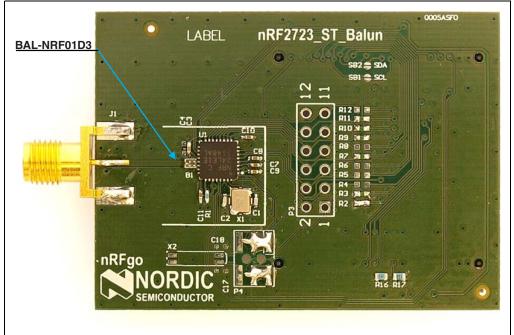


Figure 8. Application board (courtesy of Nordic Semiconductor)



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## 3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.

Figure 9. Package dimensions (bump side view)

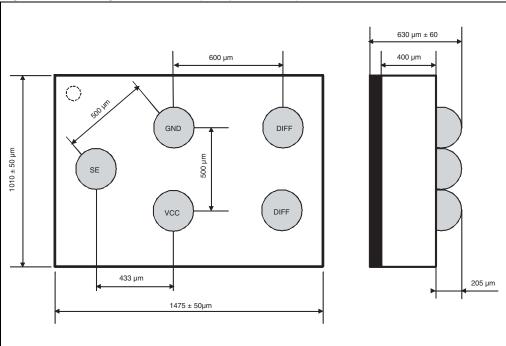


Figure 10. Footprint

Copper pad diameter:
220 µm recommended
260 µm maximum

Solder stencil opening:
220 µm recommended

Solder mask opening:
300 µm minimum

Solder mask opening:
300 µm minimum

Figure 11. Marking

Dot, ST logo

ECOPACK grade
xx = marking
z = manufacturing
location
yww = datecode

Y W W

Package information BAL-NRF01D3

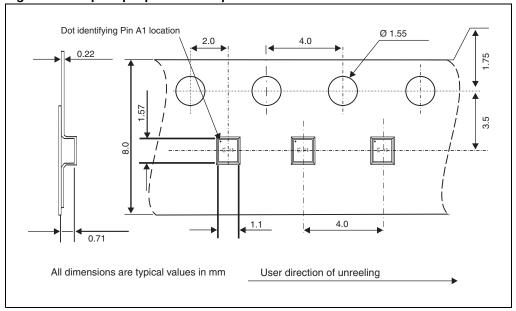


Figure 12. Flip Chip tape and reel specifications

Note: More information is available in the STMicroelectronics Application notes:

AN2348 Flip-Chip: "Package description and recommendations for use"

AN4111: "BAL-NRF01D3 matched balun with integrated harmonic filter for Nordic nRF24LE1 QFN32, nRF24AP2-1CH and nRF24AP2-8CH"



# 4 Ordering information

Table 4. Ordering information

Order code	Marking	Weight	Base Qty	Delivery mode
BAL-NRF01D3	SC	1.82 mg	5000	Tape and Reel

# 5 Revision history

Table 5. Document revision history

Date	Revision	Changes
15-Oct-2012	1	Initial release.

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